

BRGB40N65AHA

Rev.A Jan.-2026

描述 / Descriptions

TO-247 塑封封装绝缘栅双极晶体管。

Insulated-Gate Bipolar Transistor in a TO-247 Plastic Package.

特征 / Features

650V , 40A

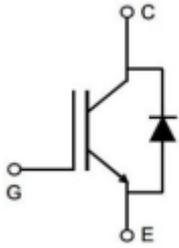
$V_{CE(SAT)} = 1.30V(\text{typ.}) @ V_{GE} = 15V, I_C = 40A$

用途 / Applications

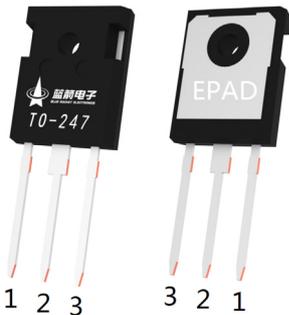
电机驱动器、不间断电源、增压器、便携式电源站。

Motor driver, Uninterrupted Power Supply, Boost, Portable power station.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : G

PIN 2、EPAD : C

PIN 3 : E

印章代码 / Marking

见印章说明。

See Marking Instructions.

极限参数 / Absolute Maximum Ratings($T_a=25^{\circ}\text{C}$)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit	
Collector-Emitter Voltage	V_{CES}	650	V	
Gate-Emitter Voltage	V_{GES}	± 30	V	
Continuous Collector Current	I_C	$T_C=25^{\circ}\text{C}$	80	A
		$T_C=100^{\circ}\text{C}$	40	A
Pulsed Collector Current , Limited by T_{Jmax}	I_{CM}	160	A	
Continuous Diode Forward Current	I_F	$T_C=25^{\circ}\text{C}$	80	A
		$T_C=100^{\circ}\text{C}$	40	A
Diode Repetitive Peak Forward Current	I_{FRM}	160	A	
Short circuit withstand time	t_{sc}	9	μs	
Power Dissipation	P_D	395	W	
Storage Temperature Range	T_{STG}	-55 to +175	$^{\circ}\text{C}$	
Maximum Temperature for Soldering	T_L	260	$^{\circ}\text{C}$	
Maximum Junction-to-Ambient	$R_{\theta JA}$	40	$^{\circ}\text{C}/\text{W}$	
Maximum IGBT Junction-to-Case	$R_{\theta JC}$	0.38	$^{\circ}\text{C}/\text{W}$	

电性能参数 / Electrical Characteristics($T_c=25^{\circ}\text{C}$)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector-Emitter Breakdown Voltage	BV_{CES}	$I_C=1\text{mA}$ $V_{GE}=0\text{V}$	650			V
Zero Gate Voltage Collector current	I_{CES}	$V_{CE}=650\text{V}$, $V_{GE}=0\text{V}$			10	μA
Gate-Emitter Leakage Current	I_{GES}	$V_{CE}=0\text{V}$, $V_{GE}=\pm 20\text{V}$			± 200	nA
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$V_{GE}=0\text{V}$, $I_C=1\text{mA}$	4.3	5.3	6.3	V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE}=15\text{V}$, $I_C=40\text{A}$	$T_J=25^{\circ}\text{C}$	1.30	1.60	V
			$T_J=125^{\circ}\text{C}$	1.50		
			$T_J=175^{\circ}\text{C}$	1.68		
Total Gate Charge	Q_g	$V_{GE}=15\text{V}$, $V_{CC}=520\text{V}$ $I_C=40\text{A}$		320		nC
Gate to Emitter Charge	Q_{ge}			30		
Gate to Collector Charge	Q_{gc}			35		

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Turn-On Delay Time	$t_{d(on)}$	$V_{GE}=15V,$ $V_{CE}=400V$ $I_C=40A,$ $R_G=5\Omega$ Inductive Load	$T_C=25^\circ C$	32		ns
			$T_C=175^\circ C$	30		
Turn-On Rise Time	t_r		$T_C=25^\circ C$	25		ns
			$T_C=175^\circ C$	27		
Turn-Off Delay Time	$t_{d(off)}$		$T_C=25^\circ C$	187		ns
			$T_C=175^\circ C$	202		
Turn-Off Fall Time	t_f		$T_C=25^\circ C$	15		ns
			$T_C=175^\circ C$	18		
Turn-On Energy	E_{on}		$T_C=25^\circ C$	0.95		mJ
			$T_C=175^\circ C$	1.45		
Turn-Off Energy	E_{off}	$T_C=25^\circ C$	0.65		mJ	
		$T_C=175^\circ C$	1.20			
Total Switching Energy	E_{ts}	$T_C=25^\circ C$	1.60		mJ	
		$T_C=175^\circ C$	2.65			
Input Capacitance	C_{ies}	$V_{GE}=0V,$ $V_{CE}=25V$ $f=1MHz$		5660		pF
Output Capacitance	C_{oes}			260		pF
Reverse Transfer Capacitance	C_{res}			154		pF
Diode Forward Voltage	V_F	$I_F=40A$	$T_J=25^\circ C$	1.30	1.60	V
			$T_J=150^\circ C$	1.18		
			$T_C=175^\circ C$	1.10		
Diode Reverse Recovery Time	T_{rr}	$V_R=400V,$ $I_F=40A$ $di_F/dt=200A/us$ $T_C=25^\circ C$		140		ns
Diode Reverse Recovery Charge	Q_{rr}			580		nC
Diode Peak Reverse Recovery Current	I_{rm}			6		A

电参数曲线图 / Electrical Characteristic Curve

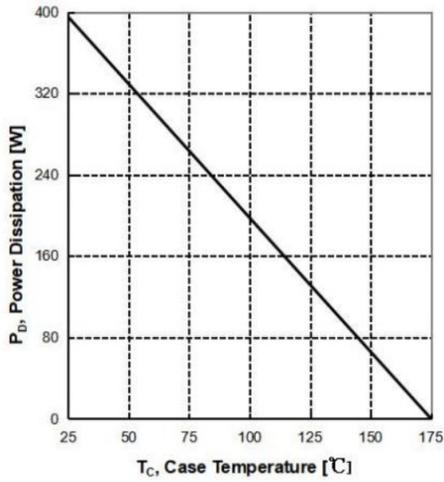


Fig. 1 TYP. Power Dissipation

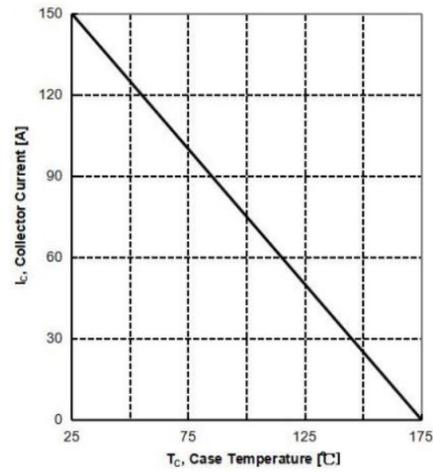


Fig. 2 Collector Current vs. Case Temperature

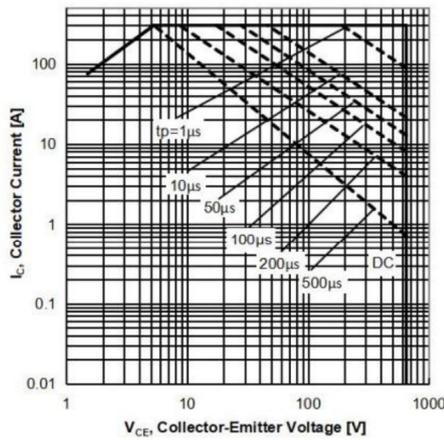


Fig. 3 Safe Operation Area

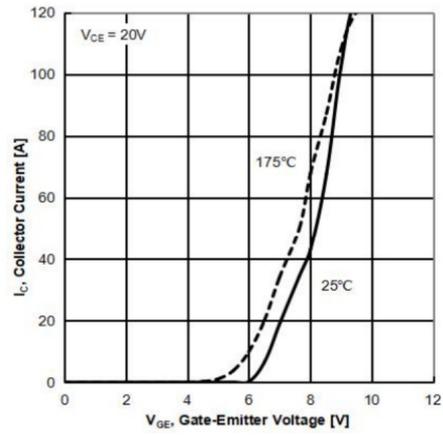


Fig. 4 TYP. Transfer Characteristics

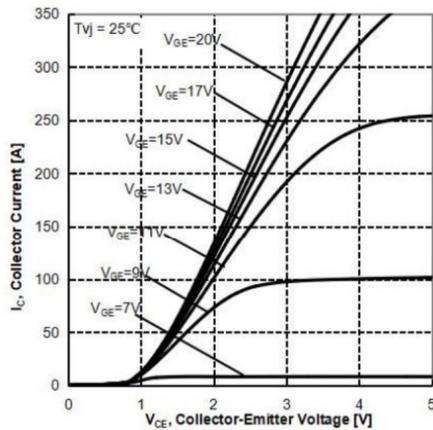


Fig. 5 TYP. Out put Characteristics

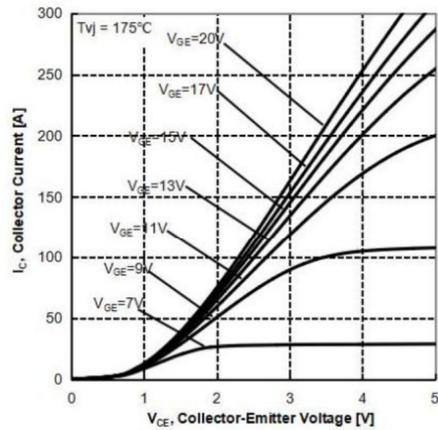


Fig. 6 Output Characteristics

电参数曲线图 / Electrical Characteristic Curve

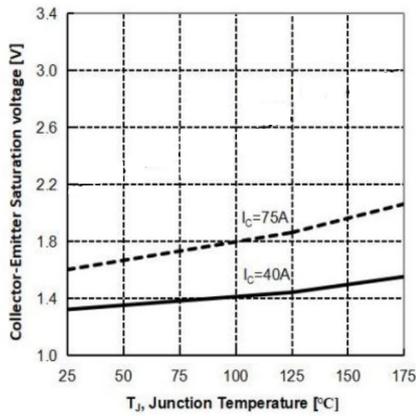


Fig. 7 Typical Collector-Emitter Saturation Voltage vs. Junction Temperature

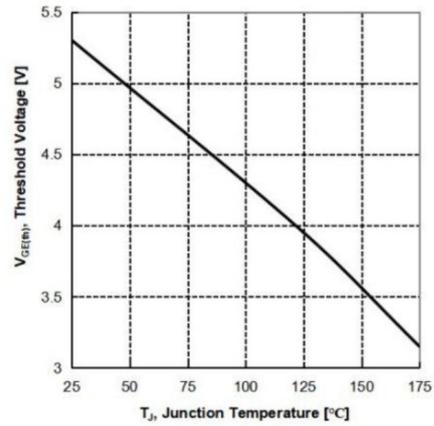


Fig. 8 Typical Gate-Emitter Threshold Voltage vs. Junction Temperature

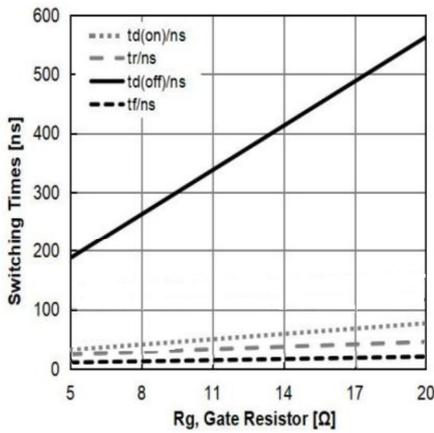


Fig. 9 TYP. Switching Times vs. Gate Resistor
($T_j=25^{\circ}\text{C}, V_{CE}=400\text{V}, V_{GE}=15\text{V}, I_C=40\text{A}$)

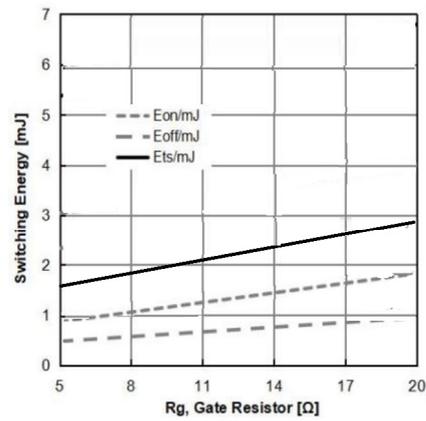


Fig. 10 TYP. Switching Energy vs. Gate Resistor
($T_j=25^{\circ}\text{C}, V_{CE}=400\text{V}, V_{GE}=15\text{V}, I_C=40\text{A}$)

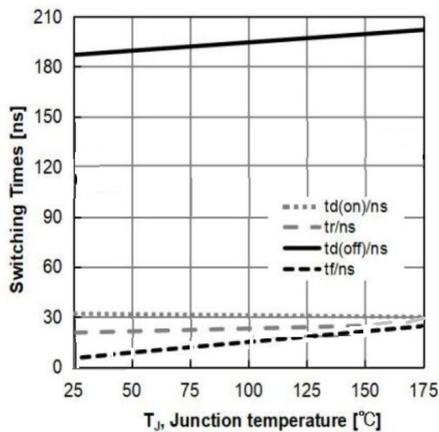


Fig. 11 TYP. Switching Times vs. Junction Temperature
($V_{CE}=400\text{V}, V_{GE}=15\text{V}, I_C=40\text{A}, R_G=5\Omega$)

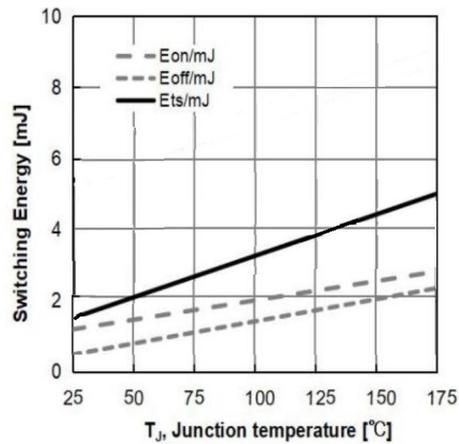


Fig. 12 TYP. Switching Energy vs. Junction Temperature
($V_{CE}=400\text{V}, V_{GE}=15\text{V}, I_C=40\text{A}, R_G=5\Omega$)

电参数曲线图 / Electrical Characteristic Curve

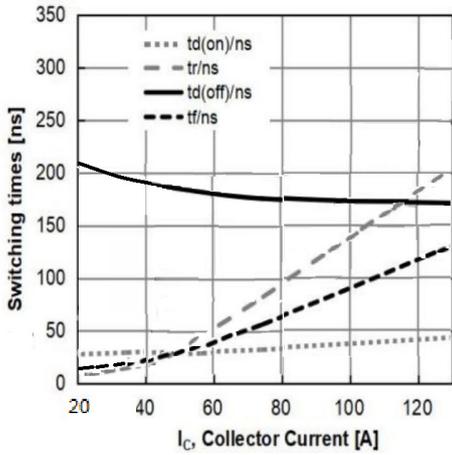


Fig. 13 TYP. Switching Times vs. Collector current
($R_g=5\Omega, V_{CE}=400V, V_{GE}=15V, T_j=25^\circ C$)

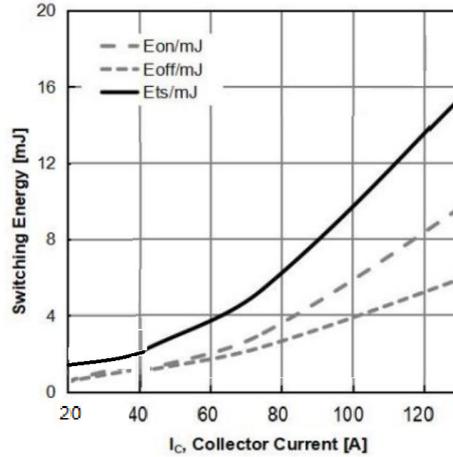


Fig. 14 TYP. Switching Energy vs. Collector current
($R_g=5\Omega, V_{CE}=400V, V_{GE}=15V, T_j=25^\circ C$)

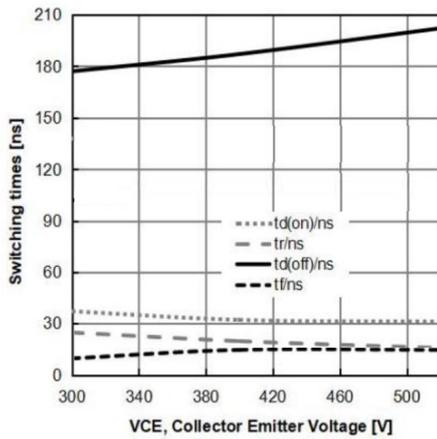


Fig. 15 TYP. Switching Times vs. VCE
($T_j=25^\circ C, I_c=40A, V_{GE}=15V, R_g=5\Omega$)

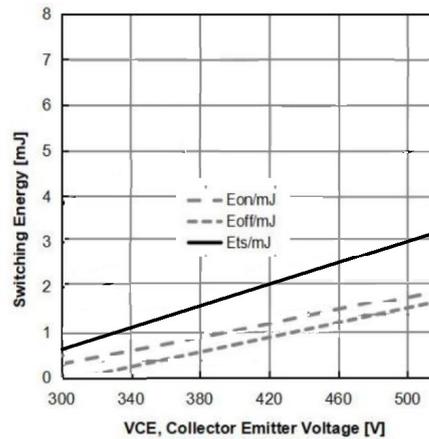


Fig. 16 TYP. Switching Energy vs. VCE
($T_j=25^\circ C, I_c=40A, V_{GE}=15V, R_g=5\Omega$)

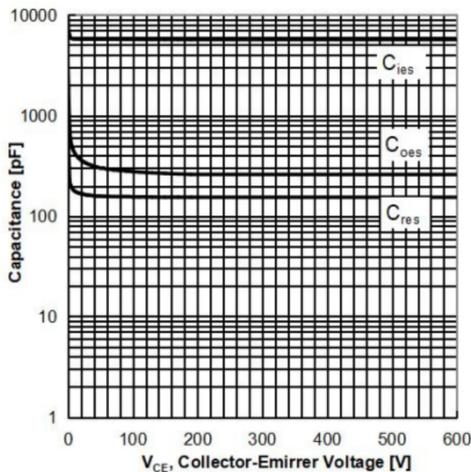


Fig. 17 TYP. Capacitance vs. Collector-Emirrer Voltage

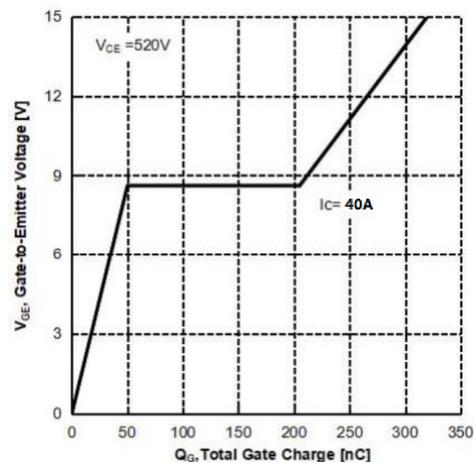


Fig. 18 TYP. Gate Charge

电参数曲线图 / Electrical Characteristic Curve

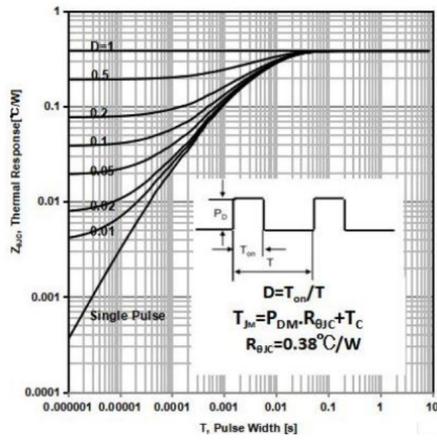
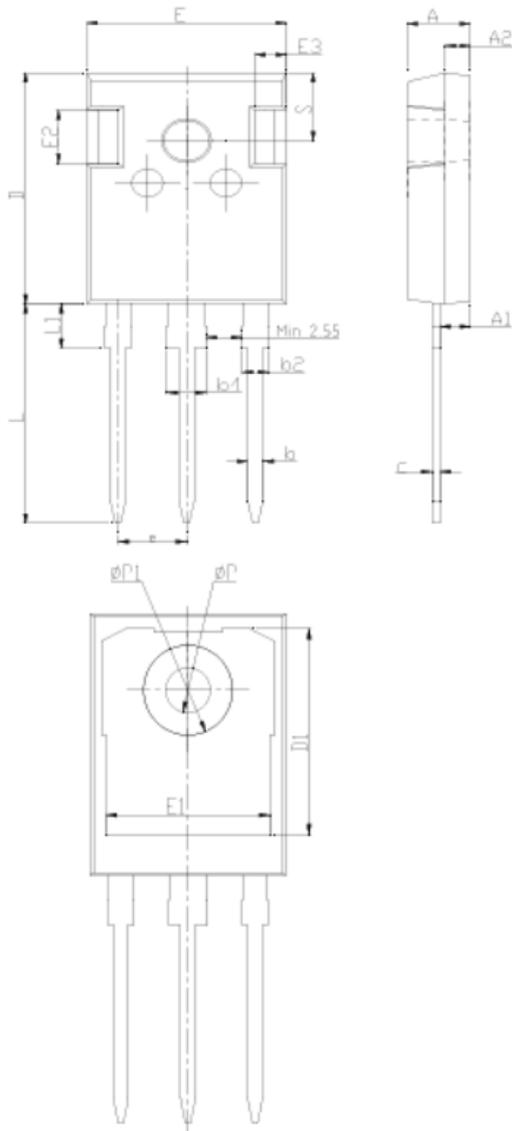


Fig. 19 TYP. Gate Charge

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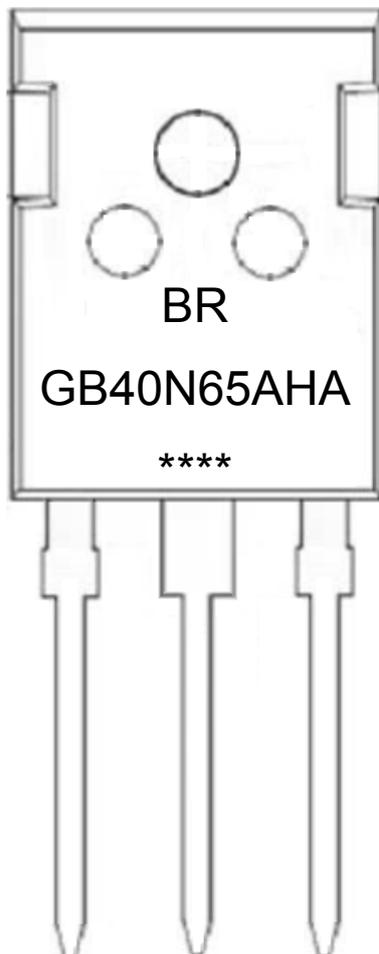
外形尺寸图 / Package Dimensions



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.70	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44BSC		
L	19.62	19.92	20.22
L1	-	-	4.30
φP	3.40	3.60	3.80
φP1	-	-	7.30
S	6.15BSC		

印章说明 / Marking Instructions



说明：

BR： 为公司代码

GB40N65AHA： 为型号代码

****： 为生产批号代码，随生产批号变化

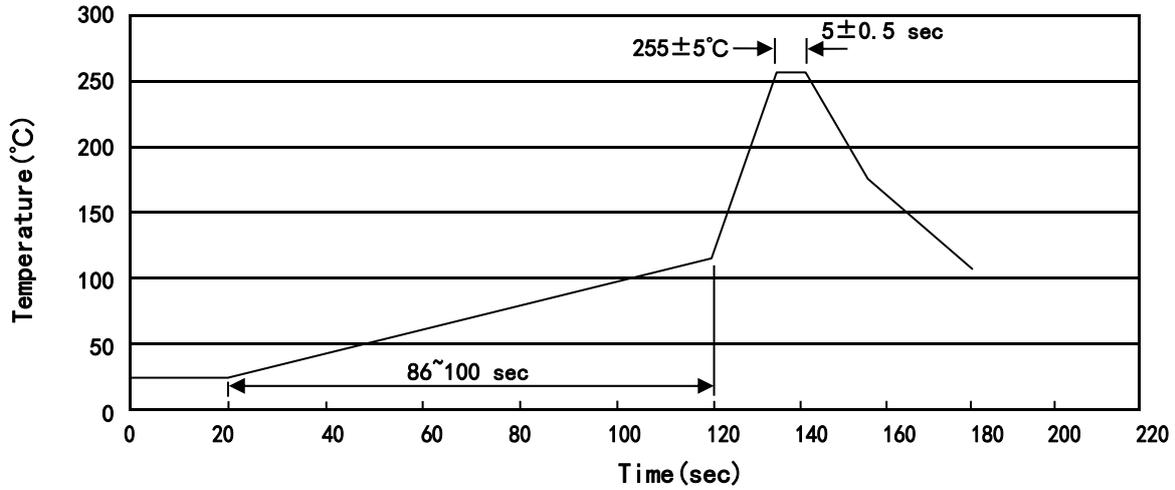
Note:

BR: Company Code

GB40N65AHA: Product Type Code

****: Lot No. Code, code change with Lot No.

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

套管包装 / TUBE

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Tube 只/套管	Tubes/Inner Box 套管/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Tube 套管	Inner Box 盒	Outer Box 箱
TO-247	30	15	450	5	2250	520×44×6	580×158×55	595×300×178

使用说明 / Notices

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